

Filename: PMP4700REVB_bom.xls							
Date: 02/22/2010							
PMP4700REVB BOM							
COUNT	RefDes	Value	Description	Size	Part Number	MFR	Area
2	C1	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106MT	TDK	83,600
5	C3	330uF	Capacitor, Alum, 25V, 1.43Arms, 20%	0.315 inch	25ZLG330M10x12.5	Rubycon	94,025
	C4	330uF	Capacitor, Alum, 25V, 1.43Arms, 20%	0.315 inch	25ZLG330M10x12.5	Rubycon	94,025
	C5	330uF	Capacitor, Alum, 25V, 1.43Arms, 20%	0.315 inch	25ZLG330M10x12.5	Rubycon	94,025
	C6	330uF	Capacitor, Alum, 25V, 1.43Arms, 20%	0.315 inch	25ZLG330M10x12.5	Rubycon	94,025
	C7	10uF	Capacitor, Ceramic, 25V, X7R, 15%	1210	C3225X7R1E106MT	TDK	83,600
4	C8	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475MT	TDK	83,600
	C9	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475MT	TDK	83,600
1	C10	0.33uF	Capacitor, Ceramic, 50V, X5R, 15%	0805	Std	TDK	10560
	C11	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475MT	TDK	83,600
1	C12	220pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	5650
1	C13	0.22uF	Capacitor, Ceramic, 16V, X7R, 15%	0603	std	std	5650
1	C14	270pF	Capacitor, Ceramic, 50V, NPO, 5%	0603	std	std	5650
1	C15	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	std	std	5650
1	C16	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	std	std	5650
1	C17	47pF	Capacitor, Ceramic, 50V, COG, 15%	0603	std	std	5650
	C18	330uF	Capacitor, Alum, 25V, 1.43Arms, 20%	0.315 inch	25ZLG330M10x12.5	Rubycon	94,025
	C100	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	C3225X7R1H475MT	TDK	83,600
1	D1	MBR20L60CT	Diode, Dual Schottky, 20A, 60V	TO220	MBR20L60CT	On Semi	110700
1	D2	6.8V	Diode, Zener, 6.8V	SOD-323	MMSZ5235BT1	Diodes	195000
1	D3	4.7V	Diode, Zener, 4.7V	SOD-323	MMSZ5230BT1	Diodes	195000
2	HS1	504222B00000G	Heatsink, TO-220/218 veritcal	0.640 x 0.640 inch	634-xxxAyy	Wakefield	448.9
	HS3	504222B00000G	Heatsink, TO-220/218 veritcal	0.640 x 0.640 inch	634-xxxAyy	Wakefield	448.9
2	J1	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST	70125
	J2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST	70125
1	L1	22uH	Inductor, Toroid, 22uH	1.700 Dia.	JA4472-AL	Coilcraft	2544690
2	Q1	MMBT2222A	Bipolar, NPN, 40V, 600mA	SOT23	MMBT2222ALT1	ON Semi	14105
1	Q2	IPP084N06L3G	MOSFET, N-ch, 60V, 50A, 8.1 milliOhms	TO-220	IPP084N06L3G	Infineon	110700
1	Q3	MMBT2907	Bipolar, PNP, 60V, 600mA	SOT23	MMBT2907LT1	On Semi	14105
	Q5	MMBT2222A	Bipolar, NPN, 40V, 600mA	SOT23	MMBT2222ALT1	On Semi	14105

1	R1	10	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R2	374K	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R3	3.9	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
2	R4	20K	Resistor, Chip, 1/16W, 1%	0805	Std	Std	10560
	R5	20K	Resistor, Chip, 1/16W, 1%	0805	Std	Std	10560
1	R6	1K	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R7	0.005	Resistor, 1W, 5%	2512	STD	STD	35100
1	R8	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650
2	R9	100K	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
	R10	100K	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R11	49.9	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R12	3.65K	Resistor, Chip, 1/16W, 1%	0603	std	std	9100
1	R100	464K	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650
2	TP1	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
3	TP2	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
	TP3	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone	10
	TP4	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
2	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone	10
	TP6	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
2	TP7	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone	10
	TP8	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone	10
	TP9	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone	10
1	U1	TPS40210	IC, 4.5V-52V I/P, Current Mode Boost Ctrl	DGQ10	TPS40210DGQ	TI	38400
Notes:	1. These assemblies are ESD sensitive, ESD precautions shall be observed.						
	2. These assemblies must be clean and free from flux and all contaminants.						
	Use of no clean flux is not acceptable.						
	3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.						
	4. Ref designators marked with an asterisk (**) cannot be substituted.						
	All other components can be substituted with equivalent MFG's components.						

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